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Starn / Amended
c**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Application Serial No. 10/004,172
Filing Date October 9, 2001
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Group Art Unit 3729
Examiner A.D. Tugbang
Attorney's Docket No. MI22-1839
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate, and Bonding
Frames

RESPONSE TO FEBRUARY 11, 2003 OFFICE ACTION
and APRIL 24, 2003 NOTICE OF NON-COMPLIANT AMENDMENT

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

From: D. Brent Kenady
Tel. 509-624-4276; Fax 509-838-3424
Wells St. John P.S.
601 West First Avenue, Suite 1300
Spokane, WA 99201-3828

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MAY 9 2003

Group 3700

Responsive to the Office Action dated February 11, 2003 and the Notice of Non-Compliant Amendment dated April 24, 2003, Applicant amends and remarks as follows:

AMENDMENTS